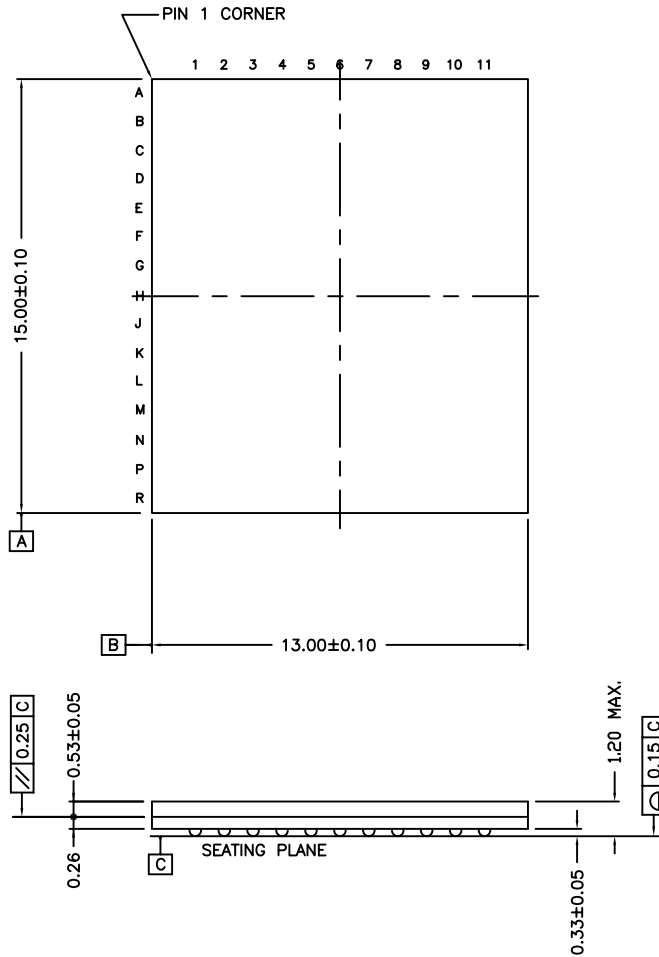
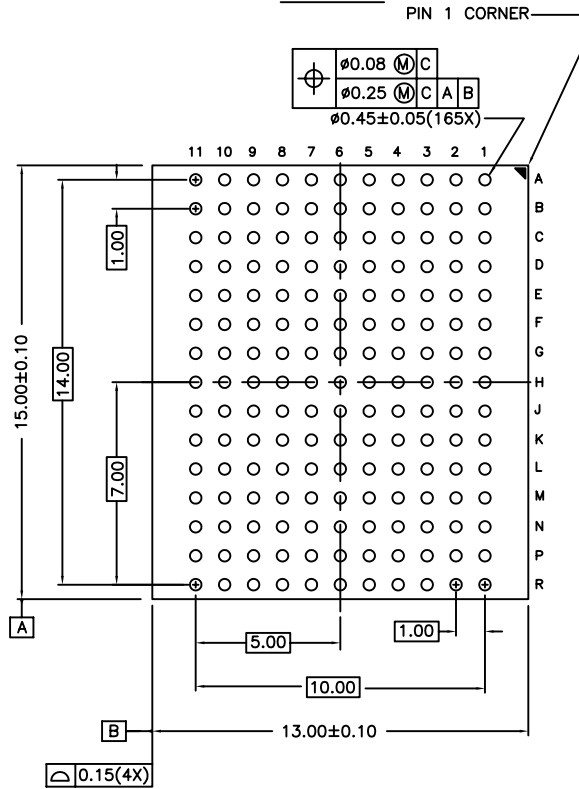


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	##	100397	NEW RELEASE	06/08/00	
1		#A	103130	CHG. PKG. HEIGHT TO 1.2 MAX./ CHG. TITLE	09/26/00	
1		#B	112596	CHG. DIM. ON BALL HEIGHT, PKG. HEIGHT, CHG. TOLERANCE ON PKG. LENGTH & WIDTH	01/11/02	
1		#C	119653	CHG. DIM. ON BALL HEIGHT, ADD MOLD CAP & SUBSTRATE DIM./ CHG. LEAD COPLANARITY	10/01/02	
1	-	#D	2741152	CONVERTED TO STANDARD DRAWING FORMAT	07/20/09	BZG
1	-	#E	3375464	CHANGED POSITION TOLERANCE FROM 0.05 TO 0.08		
1	-	#E	3375464	Update spec for sunset review, no changed	09/19/11	QAD

TOP VIEW



BOTTOM VIEW



NOTE :
JEDEC REFERENCE : MO-216 / ISSUE E

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UNLESS OTHERWISE SPECIFIED		DESIGNED BY	DATE	CYPRESS Company Confidential	
ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON:		DRAWN BY	DATE		
DECIMALS	ANGLES	TZWTMP1	07/20/09	TITLE PACKAGE OUTLINE, 165LD FBGA 13X15X1.20MM (0.45 BALL DIAMETER)	
.XX ± 0.05	± 1°	CHECKED BY	DATE		
.XXX ±		BZG	07/20/09	SIZE PART NO. DWG NO. REV	
.XXXX ±		APPROVED BY	DATE		
		TZW	07/20/09	A BB165A 51-85122 *E	
		APPROVED BY	DATE		
		QAD	07/20/09	SCALED TO FIT ENG'G REV ENG-00 SHEET 1 OF 1	
		CMG	07/20/09		